

the heat sink plate has concavo-convex portions formed on an exposed surface thereof and is disposed [so as to be opposed] to make direct contact with a main surface on which semiconductor elements of the semiconductor chip are formed; and
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the heat sink plate is so formed that the convex portions do not protrude from the surface of the sealing member to the outside.

and C

3. (Amended) [The semiconductor device according to claim 1] A semiconductor device comprising:
a substrate;
a semiconductor chip mounted on the substrate;
external electrodes provided on the back of the substrate for connecting electrodes
of the semiconductor chip to the outside;
a sealing member for encapsulating the semiconductor chip on the substrate; and
a heat sink plate fixed by the sealing member, wherein
the heat sink plate has a concavo-convex portions formed on an exposed surface
thereof and is disposed so as to be opposed to a main surface on which semiconductor
elements of the semiconductor chip are formed and so as to adjoin the main surface with
a thin sealing member placed on the main surface [of the semiconductor chip] being
interposed therebetween; and
the heat sink plate is formed so that the convex portions do not protrude from the
surface of the seaming member to the outside.

Please cancel claim 5.